

This datasheet should be used in conjunction with the application note AN4571, GDU9X-XXXXX Series, Gate Drive Unit.

APPLICATIONS

- Used with Gate Turn-Off Thyristors in high current switching applications

KEY PARAMETERS

I_{FGM}	40A
$I_{G(ON)}$	10A
dl_{GQ}/dt	50A/ μ s

CONDITIONS - (UNLESS STATED OTHERWISE)

$V_1 = +5V$	$V_2 = +15V$	$V_3 = -15V$
Test circuit GTO	DG858BW	
GDU connection to GTO	500mm CO - AX cable type RC5327230 (2 cables in parallel)	
Test circuit emitter and gate drive emitter	Honeywell sweetspot HFE 4020 - 013	
Test circuit emitter current	30mA	
Test circuit receiver and gate drive receiver	Honeywell sweetspot HFD 3029 - 002	

ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
I_{V1}	+5V PSU current	500Hz, 50% duty cycle	-	-	5.5	A
I_{V2}	+15V PSU current	500Hz	-	-	0.70	A
I_{V3}	-15V PSU current	500Hz, $I_T = 3000A$ GTO $T_j = 125^\circ C$	-	-	12	A
$V_{1(Min)}$	+5V PSU minimum	-	3.8	-	-	V
$V_{2(Min)}$	+15V PSU minimum	-	14.0	-	-	V
$V_{3(Min)}$	-15V PSU minimum	-	14.0	-	-	V
I_{FGM}	Peak forward gate current	-	40	-	-	A
$I_{G(ON)}$	On-state gate current	-	-	10	-	A
dl_{FG}/dt	Rate of rise of positive gate current	Measured 10 - 75% I_{FGM}	-	40	-	A/ μ s
dl_{GQ}/dt	Rate of rise of negative gate current	$I_T = 3000A$, 90% $I_{G(ON)}$ - 50% I_{GQM}	-	50	-	A/ μ s

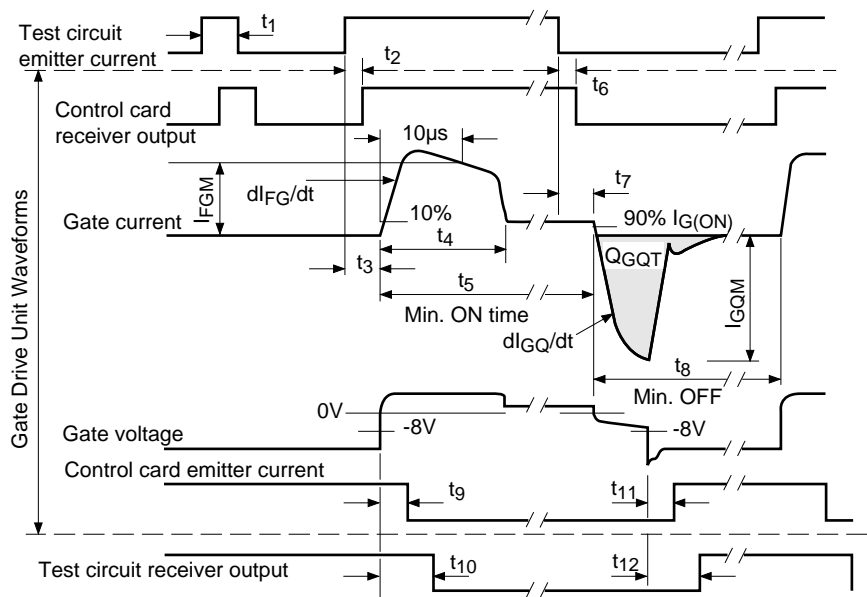
TIMING CHARACTERISTICS

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
$t_1^{*\dagger}$	No response pulse width of input signal	Adjustable by R81 + R82	2	-	3	μs
t_2	Delay time emitter current to receiver o/p	-	0.4	-	0.8	μs
$t_3^{*\dagger}$	Turn-on delay emitter current to 10% I_{FGM}	-	5.2	-	6.2	μs
t_4	I_{FGM} pulse width	-	-	25	-	μs
t_5^*	Minimum on time 10% I_{FGM} to 90% $I_{G(ON)}$	Adjustable by R37	80	-	110	μs
t_6	Receiver storage time	-	0.5	-	0.9	μs
t_7	Turn-off delay. Emitter current to 90% $I_{G(ON)}$	-	1.5	-	2.3	μs
t_8^*	Minimum off time 90% $I_{G(ON)}$ to 10% I_{FGM}	Adjustable by R38	80	-	110	μs
t_9	Delay time Gate volts to o/p emitter current	-	-	0.1	-	μs
t_{10}	Turn-off delay Gate volts to test receiver o/p	-	-	0.7	-	μs
t_{11}	Storage time Gate volts to o/p emitter current	Measured at low I_{GQM}	-	0.1 ¹	-	μs
t_{12}	Turn-on delay Gate volts to test receiver o/p	Measured at low I_{GQM}	-	0.8 ¹	-	μs

* t_1, t_3, t_5, t_8 are factory settings.

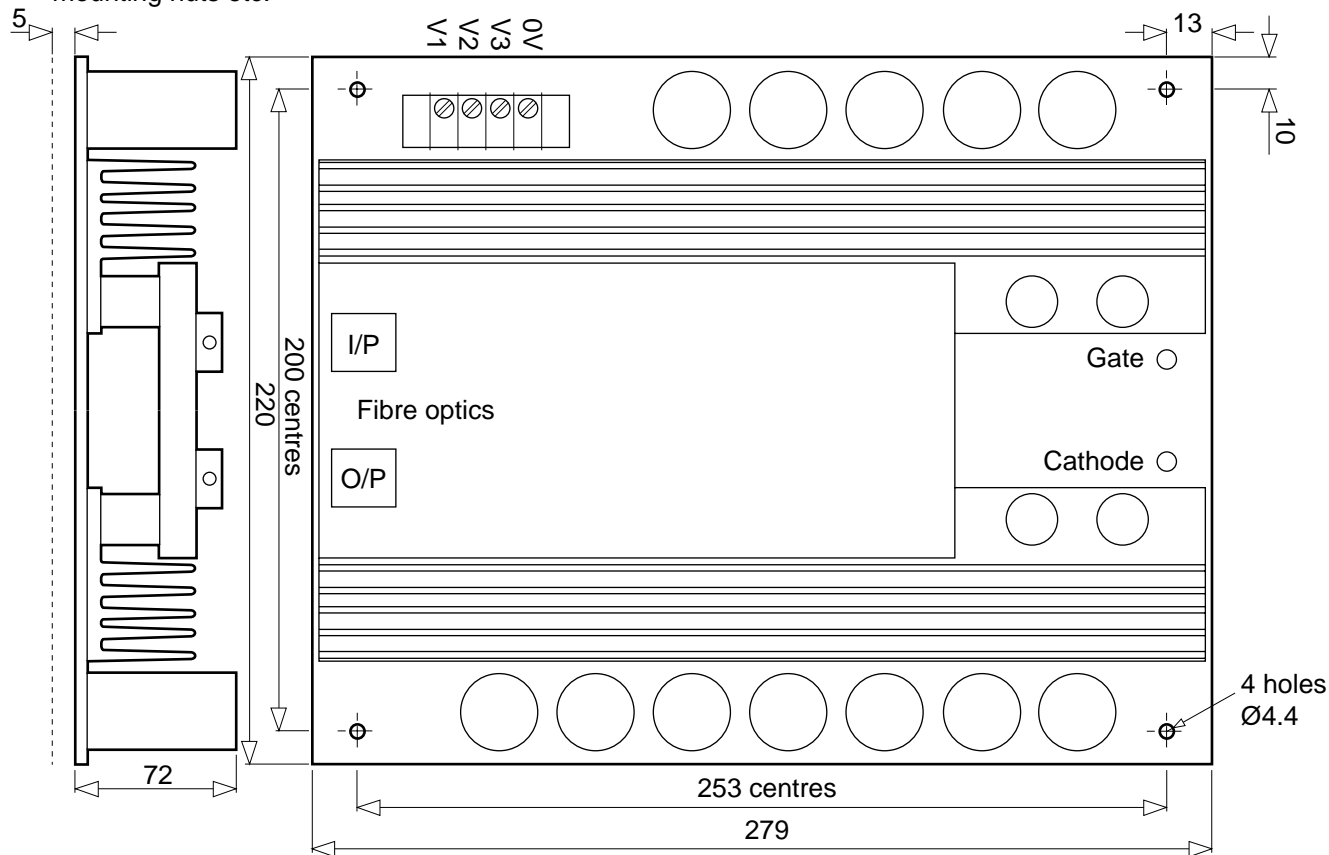
\dagger Adjustment of t_1 alters t_3 .

1. Varies with I_{GQM} due to gate lead impedance.



OUTLINE

Clearance underneath P.C.B. for
mounting nuts etc.



Weight: 2.12Kg

All dimensions in mm, unless stated otherwise. DO NOT SCALE.

POWER ASSEMBLY CAPABILITY

The Power Assembly group was set up to provide a support service for those customers requiring more than the basic semiconductor, and has developed a flexible range of heatsink / clamping systems in line with advances in device types and the voltage and current capability of our semiconductors.

We offer an extensive range of air and liquid cooled assemblies covering the full range of circuit designs in general use today. The Assembly group continues to offer high quality engineering support dedicated to designing new units to satisfy the growing needs of our customers.

Using the up to date CAD methods our team of design and applications engineers aim to provide the Power Assembly Complete solution (PACs).

DEVICE CLAMPS

Disc devices require the correct clamping force to ensure their safe operation. The PACs range offers a varied selection of pre-loaded clamps to suit all of our manufactured devices. This include cube clamps for single side cooling of 'T' 22mm

Clamps are available for single or double side cooling, with high insulation versions for high voltage assemblies.

Please refer to our application note on device clamping, AN4839

HEATSINKS

Power Assembly has it's own proprietary range of extruded aluminium heatsinks. They have been designed to optimise the performance of our semiconductors. Data with respect to air natural, forced air and liquid cooling (with flow rates) is available on request.

For further information on device clamps, heatsinks and assemblies, please contact your nearest Sales Representative or the factory.



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Target Information: This is the most tentative form of information and represents a very preliminary specification. No actual design work on the product has been started.

Preliminary Information: The product is in design and development. The datasheet represents the product as it is understood but details may change.

Advance Information: The product design is complete and final characterisation for volume production is well in hand.

No Annotation: The product parameters are fixed and the product is available to datasheet specification.

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